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**Koppal et al.**

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(54) **ELECTRONIC DEVICE HAVING COVERING SUBSTRATE CARRYING ACOUSTIC TRANSDUCER AND RELATED TECHNOLOGY**

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(\*) Notice: Subject to any disclaimer, the term of this  
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(57) **ABSTRACT**

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(52) **U.S. Cl.**

CPC ..... **H04R 1/06** (2013.01); **H04R 1/323**  
(2013.01); **H04R 2499/15** (2013.01)

(58) **Field of Classification Search**

None

See application file for complete search history.

An electronic device in accordance with a particular embodiment of the present technology includes a rigid covering substrate, an acoustic port extending through the covering substrate, an acoustic transducer carried by the covering substrate, and another electronic component (e.g., a touch sensor or an antenna) also carried by the covering substrate. The electronic device can also include processing circuitry and an array of electrodes through which the acoustic transducer and the other electronic component are electrically connected to the processing circuitry. The array of electrodes can be part of a flexible circuit board extending between a contact region of the covering substrate and the processing circuitry. The transducer lead can extend between a region of the covering substrate including the acoustic port and the contact region.

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**20 Claims, 4 Drawing Sheets**

